

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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# 2SD1922

Silicon NPN Epitaxial

**RENESAS**

ADE-208-1160 (Z)

1st. Edition

Mar. 2001

## Application

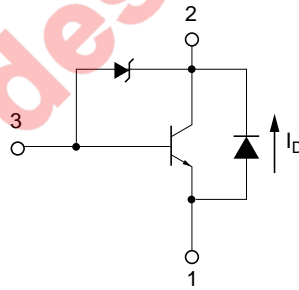
Low frequency power amplifier

## Outline

TO-92MOD



- 1. Emitter
- 2. Collector
- 3. Base



## Absolute Maximum Ratings (Ta = 25°C)

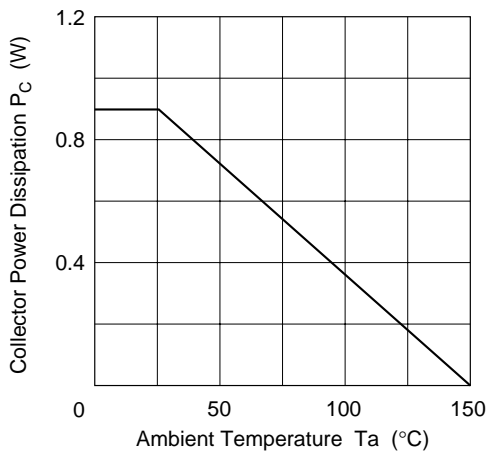
Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	25	V
Collector to emitter voltage	$V_{CEO}$	25	V
Emitter to base voltage	$V_{EBO}$	6	V
Collector current	$I_C$	0.8	A
Collector peak current	$i_{c (peak)}$	1.5	A
E to C diode forward current	$I_D$	0.8	A
Collector power dissipation	$P_C$	0.9	W
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

## Electrical Characteristics (Ta = 25°C)

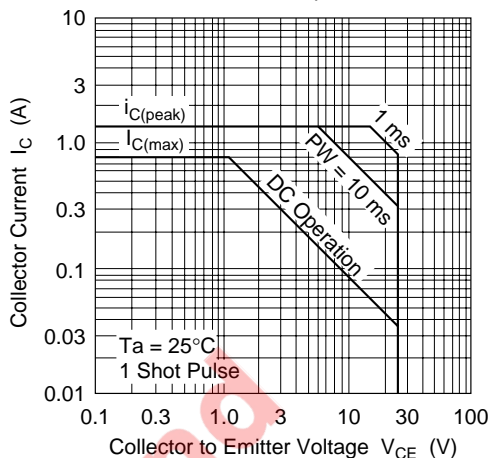
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	25	—	—	V	$I_C = 10 \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	25	—	35	V	$I_C = 1 \text{ mA}, R_{BE} = \infty$
Collector to emitter sustaining voltage	$V_{CEO(sus)}$	25	—	35	V	$I_C = 0.8 \text{ A}, R_{BE} = \infty, L = 20 \text{ mH}$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	—	—	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	$I_{CBO}$	—	—	0.2	$\mu A$	$V_{CB} = 20 \text{ V}, I_E = 0$
	$I_{CEO}$	—	—	0.5	$\mu A$	$V_{CE} = 20 \text{ V}, R_{BE} = \infty$
Emitter cutoff current	$I_{EBO}$	—	—	0.2	$\mu A$	$V_{EB} = 5 \text{ V}, I_C = 0$
DC current transfer ratio	$h_{FE}$	250	—	1200		$V_{CE} = 2 \text{ V}, I_C = 0.1 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	0.3	V	$I_C = 0.8 \text{ A}, I_B = 80 \text{ mA}^{*1}$
E to C diode forward voltage	$V_D$	—	—	1.1	V	$I_D = 0.8 \text{ A}^{*1}$

Note: 1. Pulse test

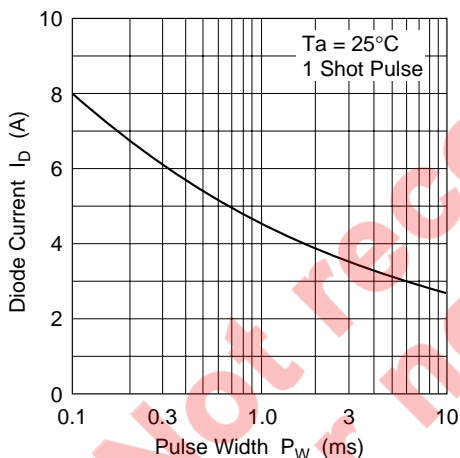
Maximum Collector Dissipation Curve



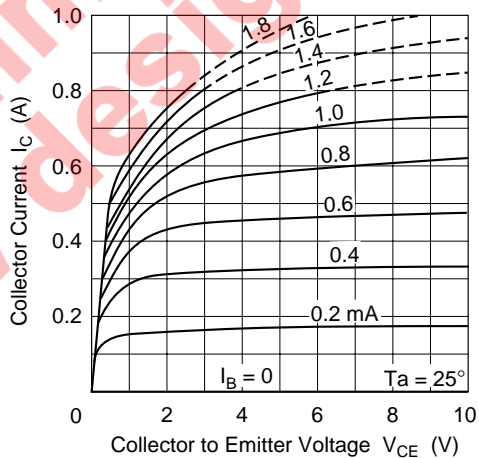
Area of Safe Operation

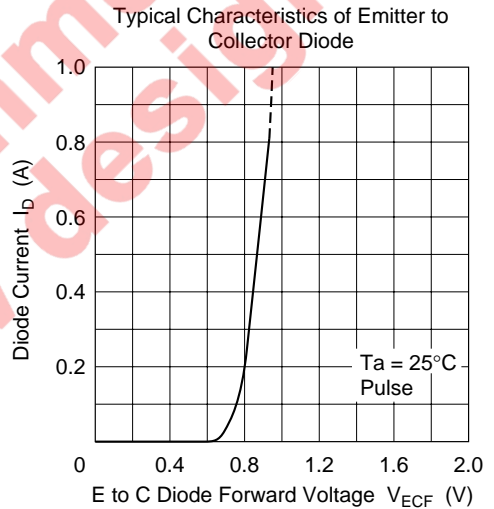
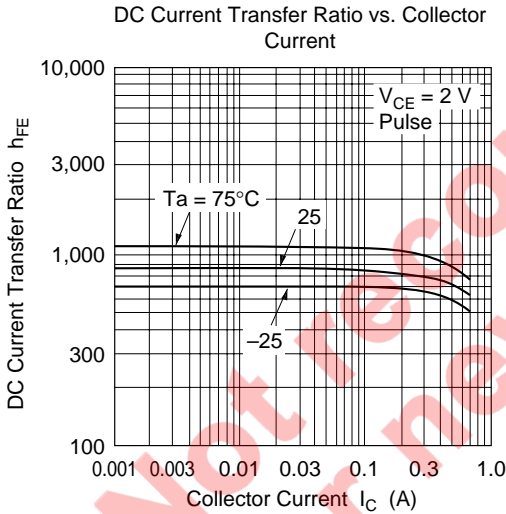
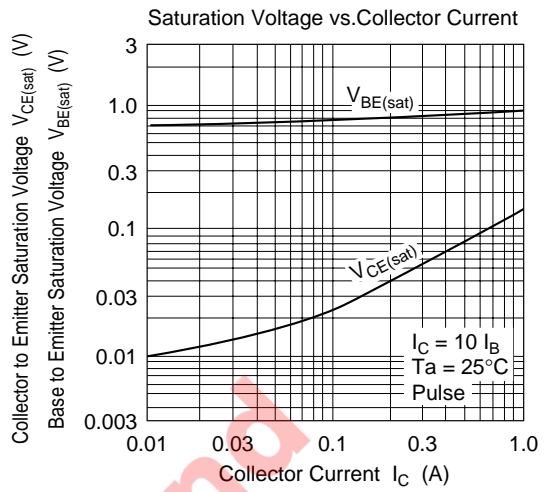
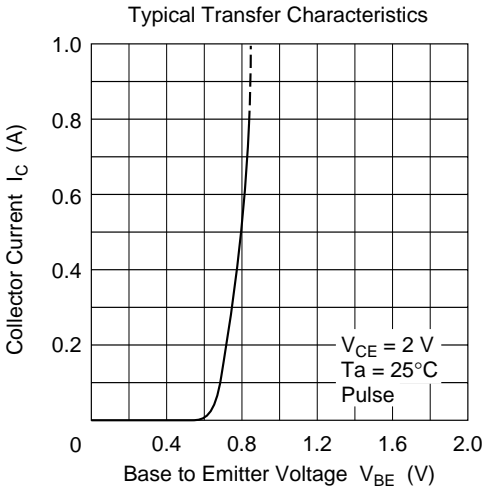


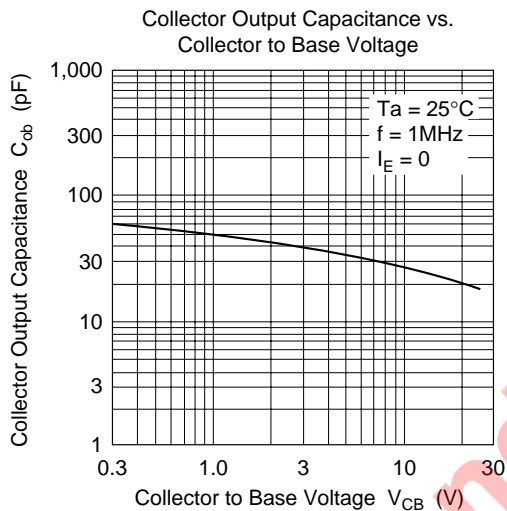
Area of Safe Operation of Emitter to Collector Diode



Typical Output Characteristics







Not recommended  
for new design





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